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(71) Applicant (for all designated States except US): **LAM RESEARCH CORPORATION** [US/US]; 4650 Cushing Parkway, Fremont, CA 94538 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **DORDI, Yezdi** [US/US]; 104 Walter Hays Drive, Palo Alto, CA 94303 (US). **THIE, William** [ID/US]; 707 Continental Circle #2221, Mountain View, CA 94040 (US). **VASKELIS, Algirdas** [LT/LT]; Pasilaiciu 18-96 Lt-2011, Vinius, Lithuania (LT). **NORKUS, Eugenijus** [LT/LT]; Zirgo1-29 Lt-10221, Vilnius, Lithuania (LT). **JACIAUSKIENE,**

Jane [LT/LT]; Architektu 176-22 Lt-04206, Vilnius, Lithuania (LT).

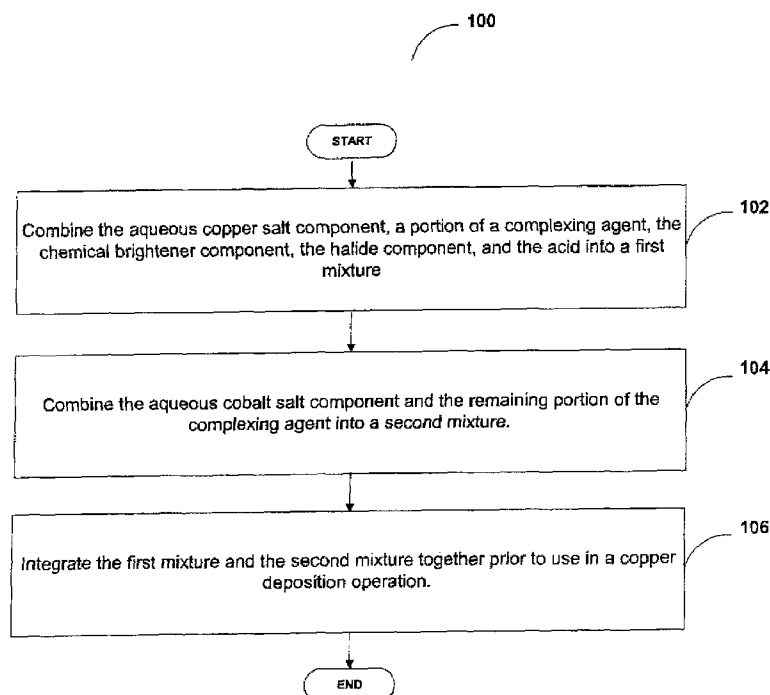
(74) Agent: **GENCARELLA, Michael, L.**; Martine Penilla & Gencarella, 710 Lakeway Drive, Suite 200, Sunnyvale, CA 94085 (US).

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(54) Title: PLATING SOLUTIONS FOR ELECTROLESS DEPOSITION OF COPPER



(57) Abstract: An electroless copper plating solution is disclosed herein. The solution includes an aqueous copper salt component, an aqueous cobalt salt component, a polyamine-based complexing agent, a chemical brightener component, a halide component, and a pH-modifying substance in an amount sufficient to make the electroless copper plating solution acidic. A method of preparing an electroless copper solution is also provided.

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